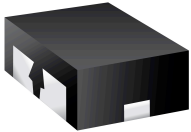


MATERIAL DECLARATION SHEET



Material Number	CGF0804 Series			
Product Line	Chipguard			
Compliance Date	2014.07.02			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite	Ferrite	0.4355	Iron oxide	1309-37-1	78.39%	28.99%	36.98%
				Nickel oxide	1313-99-1	10.68%	3.95%	
				Zinc oxide	1314-13-2	10.92%	4.04%	
2	Termination	Termination	0.0160	Silver	7440-22-4	100.00%	1.36%	1.36%
3	Thin Film Structure	Dielectric Interlayer	0.5154	Polymer	Trade secret	24.47%	10.71%	43.76%
		Dielectric Interlayer		Polymer	Trade secret	61.91%	27.09%	
		Conductor		Copper	7440-50-8	13.62%	5.96%	
4	Ferrite	Ferrite	0.1461	Iron oxide	1309-37-1	77.26%	9.58%	12.40%
				Nickel oxide	1313-99-1	12.02%	1.49%	
				Zinc oxide	1314-13-2	10.73%	1.33%	
5	Paste	Paste	0.0152	Epoxy	Trade secret	31.16%	1.29%	4.14%
5	Overcoat	Overcoat	0.0173	Polymer(Epoxy)	Trade secret	35.51%	1.47%	
5	End Termination	Termination	0.0162	Silver	7440-22-4	33.33%	1.38%	
6	External Electrode	External Electrode	0.0090	Nickel	7440-02-0	55.88%	0.76%	1.36%
			0.0071	Tin	7440-31-5	44.12%	0.60%	
Total weight			1.1778					

This Document was updated on: **2014.07.02**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.